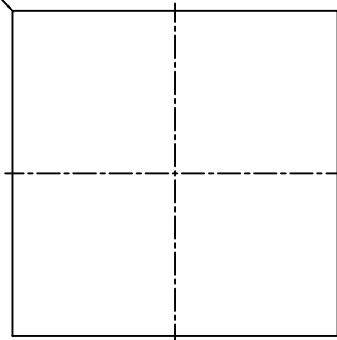


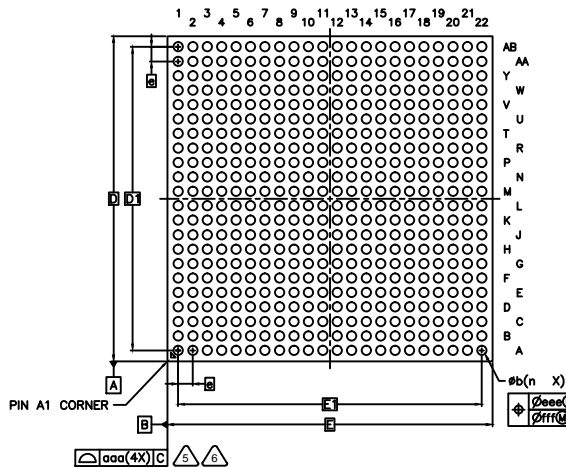
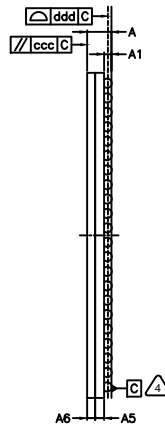


TOP VIEW

PIN A1 CORNER



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Package:		MFC LFBGA		
Body Size:	X Y	E D	18,000 18,000	
Ball Pitch:	e	0.800		
Total Thickness:	A	1.225	1.344	1.463
Mold Cap Thickness:	A6	0.450 Ref.		
Substrate Thickness:	A5	0.494 Ref.		
Ball Diameter:		0.500		
Stand Off:	A1	0.300	0.400	0.500
Ball Width:	b	0.450	0.500	0.550
Package Edge Tolerance:	aaa	0.150		
Mold Parallelism:	ccc	0.200		
Coplanarity:	ddd	0.200		
Ball Offset (Package):	eee	0.150		
Ball Offset (Ball):	fff	0.080		
Ball Count:	n	484		
Edge Ball Center to Center:	X Y	E1 D1	16.800 16.800	

## Product Name

LAV-AT-E30-CBG484

LAV-AT-E30B-CBG484

LAV-AT-G30-CBG484

## NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM  $\square$ .
- PRIMARY DATUM  $\square$  AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.5

Title: Package Outline Drawing

Pkg Type: FCCSP

Document No:

Product Family: LAV-AT

Pin Count: 484

POD-250013

Product Name: See Table

Pkg Size: 18x18 mm

Rev: D

PAGE: 3/3

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